

Title (en)

METHOD FOR PRODUCING INSULATIONS OF ELECTRIC CONDUCTORS BY MEANS OF POWDER COATING

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ISOLIERUNGEN ELEKTRISCHER LEITER MITTELS PULVERBESCHICHTUNG

Title (fr)

PROCEDE DE REALISATION D'ISOLATIONS DE CONDUCTEURS ELECTRIQUES PAR RECOUVREMENT AVEC UNE POUDRE

Publication

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Application

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Abstract (en)

[origin: WO0148763A2] The aim of the invention is to provide a method for producing insulations of electric conductors by means of powder coating which is characterized by an improved aging behavior compared to glass-mica or cast resin insulations and to also provide a powder appropriate for use in the inventive method. To this end, the powder is applied repeatedly up to a layer thickness of ≤ 10 mm in the form of subsequent individual layers and every individual layer is intermediately thermocured before the next individual layer is applied. The curing time observed for the intermediate curing of every individual layer corresponds to 2 to 10 times the gel time of the powder used. The entire insulating structure is then finally cured. The result of an electric life test of various test specimen, insulated with the epoxide resin powder that contains a fine filler and applied according to the inventive method, is shown in the only figure.

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